



#13/Response
3/27/03
PATENT

Shm H

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kloster, et al.

Serial No.: 09/820,079

Filed: March 28, 2001

For: STRUCTURE IN A
MICROELECTRONIC DEVICE
INCLUDING A BI-LAYER FOR A
DIFFUSION BARRIER AND AN
ETCH STOP LAYER

Examiner: Thomas J. Magee

Group Art Unit: 2811

Attorney Docket No.: 42390.P11026

CERTIFICATE OF MAILING

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RESPONSE AFTER FINAL REJECTION

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Hon. Assistant Commissioner for Patents
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Sir:

This Response After Final Rejection is in response to the Final Office Action mailed January 22, 2003 and is submitted to put the pending case into condition for allowance thereof or into better condition for appeal. Consideration of this response is respectfully requested.